

Amendments to the Specification

Please delete paragraphs [0022] and [0023] in their entirety and replace them with the following like numbered paragraphs:

[0022] Front side heat dissipation device 20 may be coupled to the front side 13 of modular platform board 10 and in thermal communication with thermal conductors
18. Front side heat dissipation device 20 may also be configured to overlay a front side electronic component 21 (not shown) that is opposably positioned on the front side 13 in relation to a back side electronic component 12. In such a configuration, front side heat dissipation device may transfer heat from both the front side component, and the back side component (via the thermal conductors) to the cooling medium circulating through the shelf.

[0023] Configuring components on opposite sides of modular platform board may increase the density of the modular platform boards and take better advantage of the aggregate thickness allowed on both sides of the modular platform board. Opposably Opposably positioning components also may shorten the routing and transmission distances between the back side and front side component, which may improve component response and performance.